

**EXPEDITED PROCEDURE – EXAMINING GROUP 2814**

**S/N 09/733,289**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 8, 2000	Docket No.:	884.798US1
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		
Customer Number:	21186		

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**SUPPLEMENTAL AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116**

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This paper is filed in response to the Advisory Office Action mailed January 25, 2008, and is supplemental to the Response Under 37 CFR 1.116 filed December 31, 2007 filed in response to the Final Office Action mailed October 30, 2007. Please amend the application as follows:

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a three-month extension of the period for responding to the Office action, thereby moving the deadline for response from January 30, 2008 to April 30, 2008.